



**FORM PTO-1449**  
**INFORMATION DISCLOSURE STATEMENT BY APPLICANT(S)**

Docket No.: 4724-0019WOUS  
 Applicant: Seiichiro Udagawa  
 Title: CHEMICAL LIQUID SUPPLY  
 APPARATUS AND DEAERATING  
 METHOD THEREFOR

U.S. Serial No.: 10/500,121  
 U.S. Filing Date: June 25, 2004  
 Group Art Unit: 3746

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